

LTM8045 40LD -BGA-Pb 11.25mm X 6.25mm X 4.92mm-SOLDER DA (TABLE OF MATERIAL DECLARATION)

Contains > 1000ppm of Lead in the terminations

| | | | | | | | |
|----------------------|---------------------------|---------------|--------|--|--------------------------------|----------|---------|
| 1 | Substrate | Circuit Board | 0.0764 | Barium Compounds | 7727-43-7 | 0.001238 | 1.620 |
| | | | | Bismaleimide/Triazine Resin/Filler | 105391-33-1 | 0.021714 | 28.410 |
| | | | | Substances (silica Crystalline) | 1156-51-0/9003-36-5/21645-51-2 | | |
| | | | | Copper Metal | 7440-50-8 | 0.031176 | 40.790 |
| | | | | Copper Compounds | 147-14-8 | 0.000011 | 0.014 |
| | | | | Ecotoxic substances | 7440-38-2, 7440-28-0 | 0.000002 | 0.003 |
| | | | | Gold metal or alloy | 7440-57-5 | 0.000436 | 0.570 |
| | | | | Nickel | 7440-02-0 | 0.001995 | 2.610 |
| | | | | Zinc | 7440-66-6 | 0.000023 | 0.030 |
| | | | | Continuous Filament Fiber Glass | 65997-17-3 | 0.017059 | 22.320 |
| | | | | Acrylic Resin | non-disclosure | 0.002369 | 3.100 |
| | | | | Epoxy Resin | non-disclosure | 0.000013 | 0.017 |
| | | | | Chromium (III) oxide | 1308-38-9 | 0.000001 | 0.001 |
| | | | | Silica amorphous | 7631-86-9 | 0.000031 | 0.041 |
| | | | | Talc;not containing fibers like asbestos | 14807-96-6 | 0.000145 | 0.190 |
| | | | | Aromatic carbonyl compounds | non-disclosure | 0.000138 | 0.180 |
| | | | | Cyanoguanidine | 461-58-5 | 0.000004 | 0.005 |
| | | | | Calcium carbonate | 471-34-1 | 0.000002 | 0.003 |
| | | | | amine compounds | non-disclosure | 0.000018 | 0.024 |
| | | | | Leveling agent and other | non-disclosure | 0.000055 | 0.072 |
| 2 | Solder Paste | Alloy | 0.0184 | Sn | 7440-31-5 | 0.01752 | 95.000 |
| | | | | Sb | 7440-36-0 | 0.00092 | 5.000 |
| 3 | Passive/Active Components | | 0.2751 | Fe Oxide | 1317-61-9 | 0.05038 | 18.314 |
| | | | | Mn Oxide | 1317-35-7 | 0.01439 | 5.232 |
| | | | | Zn Oxide | 1314-13-2 | 0.00720 | 2.616 |
| | | | | Glass Fibers | 65997-17-3 | 0.03239 | 11.773 |
| | | | | Copper (Cu) | 7440-50-8 | 0.05782 | 21.017 |
| | | | | Tin (Sn) | 7440-31-5 | 0.02214 | 8.049 |
| | | | | Nickel (Ni) | 7440-02-0 | 0.00328 | 1.193 |
| | | | | Antimony (Sb) | 7440-36-0 | 0.00405 | 1.472 |
| | | | | Adhesive | 25068-38-6 | 0.00540 | 1.962 |
| | | | | Resins | 25053-15-0 | 0.05434 | 19.752 |
| | | | | Ceramic (Ba) Compounds | 12047-27-7 | 0.02362 | 8.587 |
| 4 | Active Ics | Silicon | 0.0017 | Silicon | 7440-21-3 | 0.00170 | 100.000 |
| 5 | Wire | Gold | 0.0002 | Au | 7440-57-5 | 0.00020 | 99.990 |
| 6 | Solder Ball | 63Sn/37Pb | 0.0765 | Sn | 7440-31-5 | 0.04820 | 63.00 |
| | | | | Pb | 7439-92-1 | 0.02831 | 37.00 |
| 7 | Encapsulation | Epoxy Resin | 0.4376 | Fused Silica | 60676-86-0 | 0.33783 | 77.200 |
| | | | | Epoxy Resin | non-disclosure | 0.03895 | 8.900 |
| | | | | Phenol Resin | non-disclosure | 0.03895 | 8.900 |
| | | | | Crystalline Silica | 14808-60-7 | 0.01313 | 3.000 |
| | | | | Carbon Black | 1333-86-4 | 0.00219 | 0.500 |
| | | | | Metal Hydroxide | non-disclosure | 0.00656 | 1.500 |
| Total Package Weight | | | 0.8859 | | | | |

Note: Composition derived from MSDS and material C of C from Vendors.Component Weight based on assembly of generic parts